



Comments	Hole Dia (mm)	Plating Thickness		Pad Dia (mm)
		Cu	Sn/Pb	
	L3	0.03-0.08	0.008	2.0
Recommended for PCB thicknesses > 1.6mm	L4	0.03-0.08	0.008	2.2
	L5	0.03-0.08	0.008	2.3
Centre Pin	L2	0.03-0.08	0.008	1.8

REVISION HISTORY			
REV	DESCRIPTION	DATE	APPROVED
1.1	Part No Issued	26/10/2006	Peter Fayers
1.2	Additional Dims	26/11/2008	P. Fayers

Status: Pending	Material: Brass/PhosBronz/PTFE		Finish: Ni/Au/Nat	Gen Tol +/- 0.20	DO NOT SCALE	
	Designed by Peter Fayers	Checked by	Approved by	Date ©2006	Date 26/10/2006	A3
	C.E.I. Ltd				BNC (F) Pressfit Hybrid 75 Ohm	
					C-SX-061 Cust Drawing	Issue 1.2 Sheet 1 / 1

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